

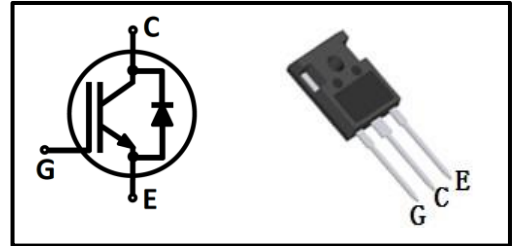
## Features

- Easy parallel switching capability due to positive temperature coefficient in  $V_{CEsat}$
- Low  $V_{CEsat}$ , fast switching
- High ruggedness, good thermal stability
- Very tight parameter distribution

## Applications

- UPS
- PFC
- PTC Heater
- Climate Compressor

Type	Marking	Package Code
MPBW50N65ES	MP50N65ES	TO-247-3



## Maximum Rated Values <sup>1</sup>

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CE}$	650	V
DC collector current <sup>2</sup>			A
$T_C=25^\circ\text{C}$	$I_C$	80	
$T_C=100^\circ\text{C}$		50	
Pulsed collector current <sup>3</sup>	$I_{Cpuls}$	200	
Diode forward current <sup>2</sup>			
$T_C=25^\circ\text{C}$	$I_F$	80	
$T_C=100^\circ\text{C}$		50	
Diode pulsed current <sup>3</sup>	$I_{Fpuls}$	200	
Short circuit withstanding time $V_{GE}=15\text{V}, V_{CC}\leq 400\text{V}, T_J\leq 150^\circ\text{C}$	$t_{SC}$	5	us
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Transient Gate-emitter voltage ( $t_p\leq 10\mu\text{s}$ )		$\pm 30$	
Power dissipation			W
$T_C=25^\circ\text{C}$	$P_{tot}$	300	
$T_C=100^\circ\text{C}$		150	
Operating junction temperature	$T_j$	-55~175	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55~150	

1:Reference standard: JESD-022 2: limited by  $T_{jmax}$  3:  $T_p$  limited by  $T_{jmax}$  ;



### Thermal Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
IGBT thermal resistance, junction-case	$R_{thJC}$	-	-	0.5	K/W
Diode thermal resistance, junction-case	$R_{thJCD}$	-	-	0.65	
Thermal Resistance, junction-ambient	$R_{thJA}$	-	-	40	

### Electrical Characteristics (at $T_j=25^\circ\text{C}$ , unless otherwise specified) Static Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=0.25mA$	650	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=50A$ $T_j=25^\circ\text{C}$	-	1.54	1.85	
		$T_j=125^\circ\text{C}$	-	1.77	-	
		$T_j=150^\circ\text{C}$	-	1.85	-	
Diode forward voltage	$V_F$	$V_{GE}=0V, I_F=50A$ $T_j=25^\circ\text{C}$	-	1.56	1.95	
		$T_j=125^\circ\text{C}$	-	1.43	-	
		$T_j=150^\circ\text{C}$	-	1.37	-	
G-E threshold voltage	$V_{GE(th)}$	$I_C=250\mu A, V_{CE}=V_{GE}$	4.0	5.0	6.0	
C-E leakage current	$I_{CES}$	$V_{CE}=650V, V_{GE}=0V$ $T_j=25^\circ\text{C}$	-	-	0.01	mA
		$T_j=150^\circ\text{C}$	-	-	1.0	
G-E leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=20V$	-	-	250	nA
Transconductance	$g_{FS}$	$V_{CE}=20V, I_C=50A$	-	27	-	S

### Dynamic Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Input capacitance	$C_{iss}$	$V_{CE}=30V,$ $V_{GE}=0V,$ $f=1MHz$	-	3050	-	pF
Output capacitance	$C_{oss}$		-	172	-	
Reverse transfer capacitance	$C_{riss}$		-	38	-	
Gate charge	$Q_G$	$V_{CC}=300V, I_C=50A,$ $V_{GE}=15V$	-	130	-	nC



### IGBT Switching Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit	
Turn-on delay time	$t_{d(on)}$	$T_j=25^{\circ}\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=50\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=10\Omega$ , Inductive load	-	104	-	ns	
Rise time	$t_r$		-	72	-		
Turn-off delay time	$t_{d(off)}$		-	218	-		
Fall time	$t_f$		-	44	-		
Turn-on energy	$E_{on}$		$T_j=150^{\circ}\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=50\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=10\Omega$ , Inductive load	-	1.17	-	mJ
Turn-off energy	$E_{off}$			-	1.74	-	
Total switching energy	$E_{ts}$			-	2.91	-	
Turn-on delay time	$t_{d(on)}$	$T_j=150^{\circ}\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=50\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=10\Omega$ , Inductive load	-	102	-	ns	
Rise time	$t_r$		-	74	-		
Turn-off delay time	$t_{d(off)}$		-	236	-		
Fall time	$t_f$		-	60	-		
Turn-on energy	$E_{on}$		$T_j=150^{\circ}\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=50\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=10\Omega$ , Inductive load	-	2.15	-	mJ
Turn-off energy	$E_{off}$			-	2.04	-	
Total switching energy	$E_{ts}$			-	4.19	-	

### Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode reverse recovery time	$t_{rr}$	$T_j=25^{\circ}\text{C}$ , $V_R=400\text{V}$ , $I_F=50\text{A}$ , $di_F/dt=600\text{A}/\mu\text{s}$	-	100	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	0.99	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	17	-	A
Diode reverse recovery time	$t_{rr}$	$T_j=150^{\circ}\text{C}$ , $V_R=400\text{V}$ , $I_F=50\text{A}$ , $di_F/dt=600\text{A}/\mu\text{s}$		155		ns
Diode reverse recovery charge	$Q_{rr}$			2.7		$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$			26		A

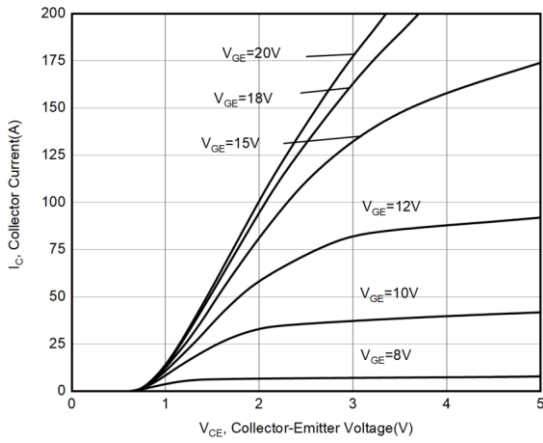


Figure 1. Typical output characteristic ( $T_j = 25^\circ\text{C}$ )

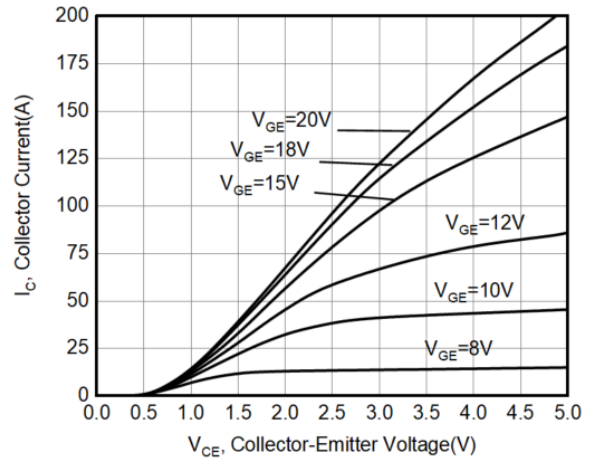


Figure 2. Typical output characteristic ( $T_j = 150^\circ\text{C}$ )

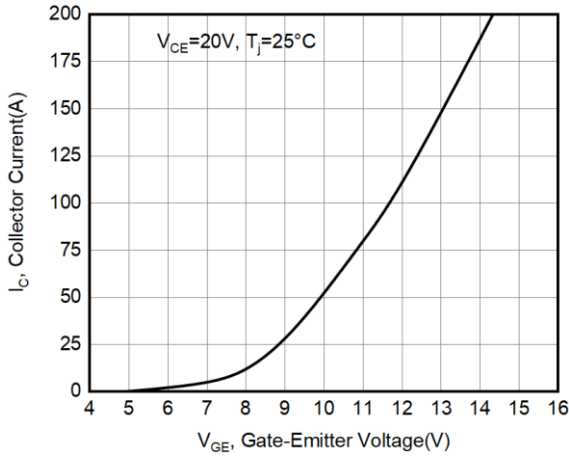


Figure 3. Typical transfer characteristic ( $T_j = 25^\circ\text{C}$ )

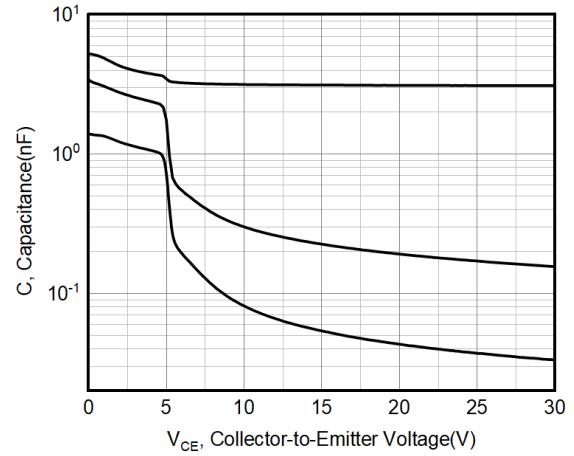


Figure 4. Capacitance characteristic ( $V_{GE} = 0\text{V}$ ,  $f = 1\text{MHz}$ )

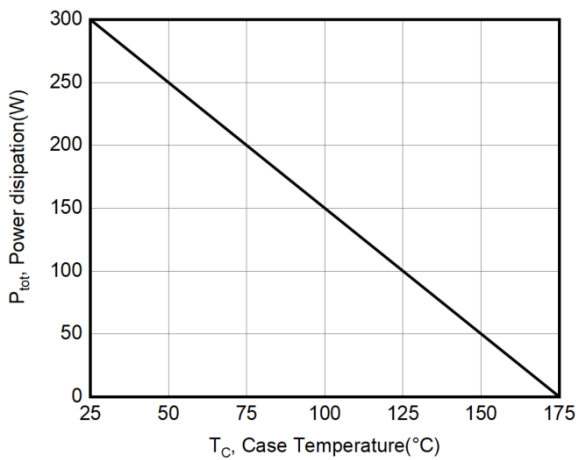


Figure 5. Power dissipation as a function of case temperature ( $T_j \leq 175^\circ\text{C}$ )

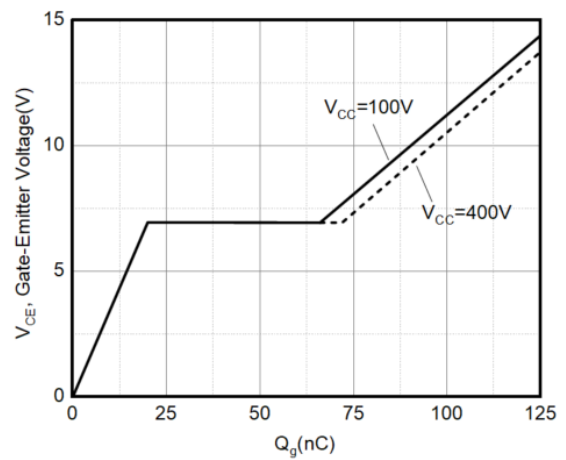


Figure 6. Typical gate charge ( $I_C = 50\text{A}$ )

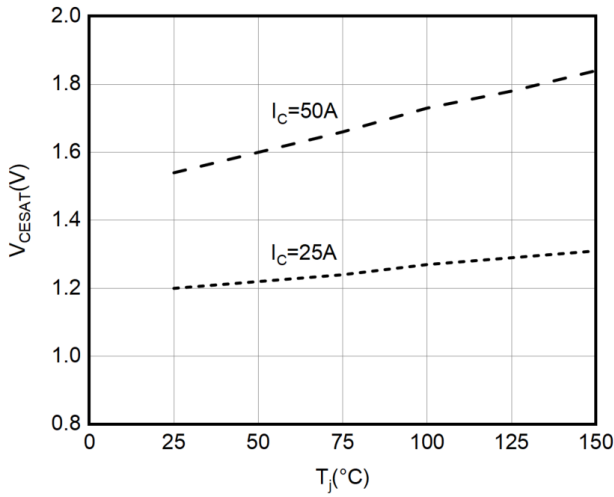


Figure 7.  $V_{CESAT}$  as a function of junction temperature ( $V_{GE}=15V$ )

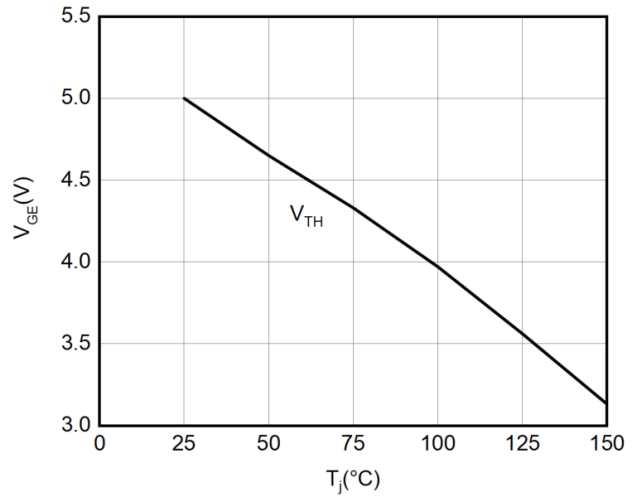


Figure 8.  $V_{TH}$  as a function of junction temperature ( $I_{CE}=250\mu A$ )

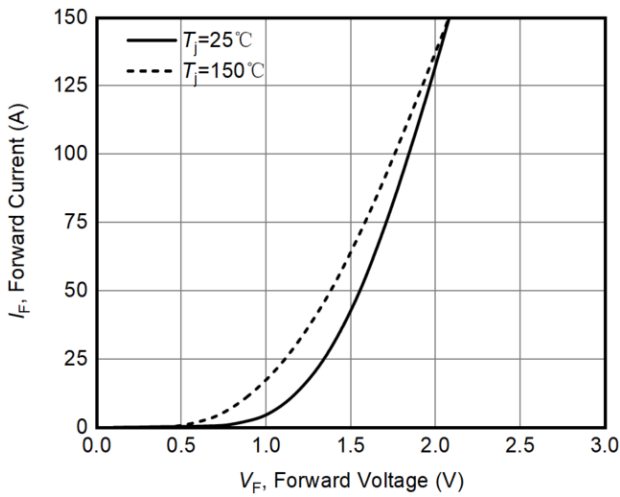


Figure 9. Typical diode forward current as a function of forward voltage

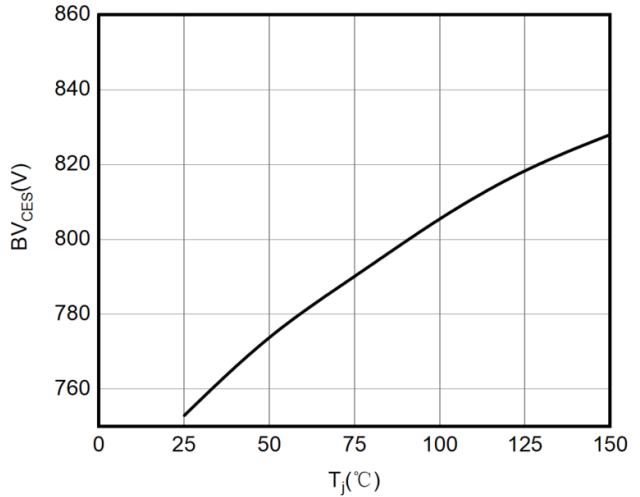


Figure 10. BV as a function of junction temperature ( $I_{CE}=250\mu A$ )

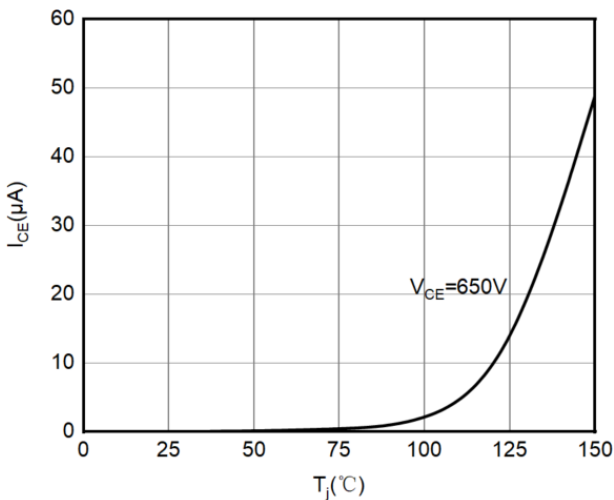


Figure 11.  $I_{CES}$  leakage current as a function of junction temperature

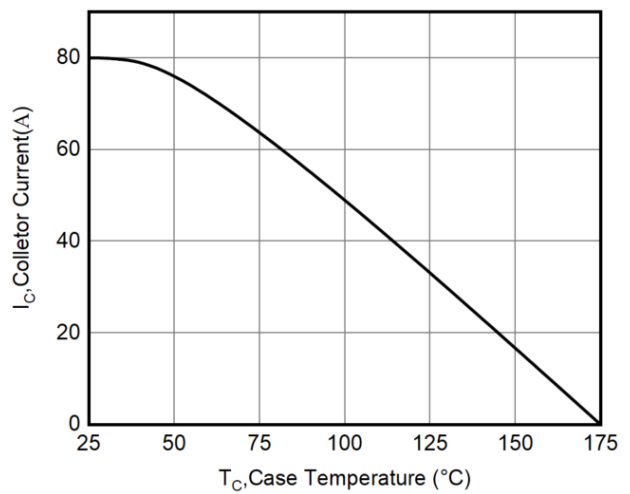
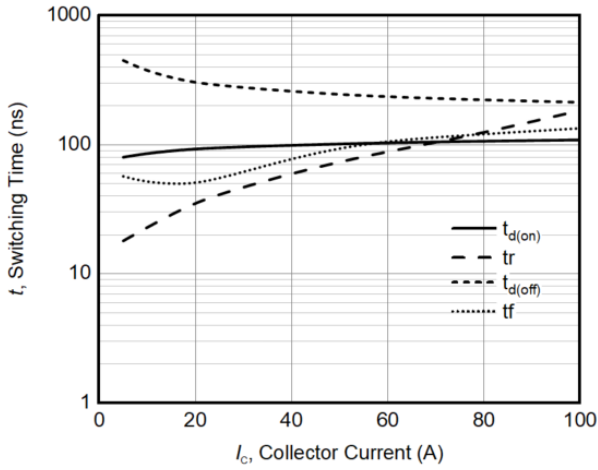
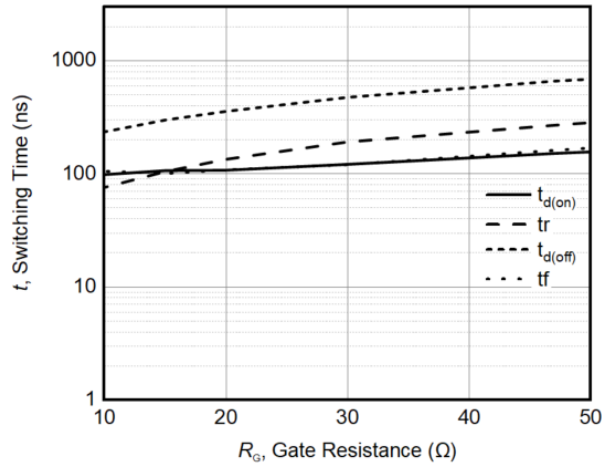


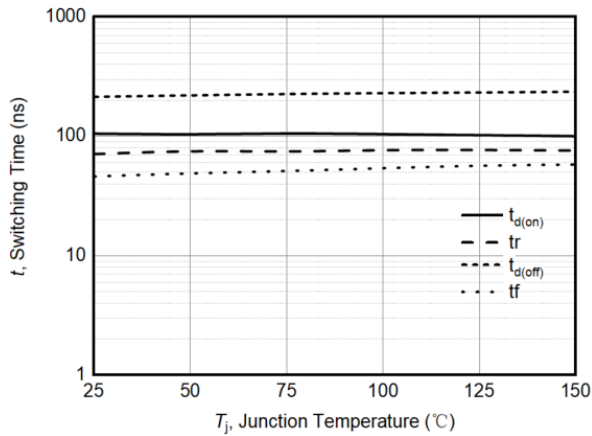
Figure 12. Collector current as a function of case temperature ( $V_{GE}\geq 15V$ ,  $T_j\leq 175^\circ C$ )



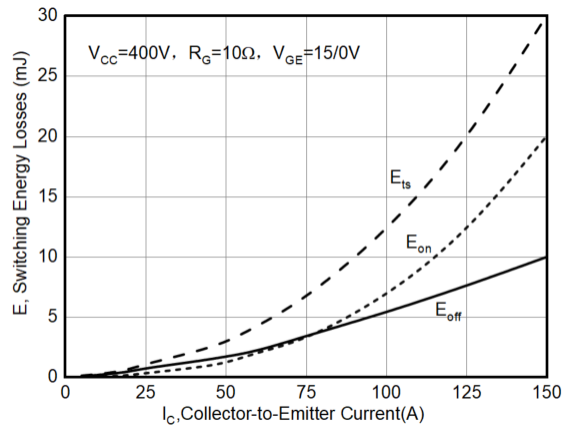
**Figure 13. Typical switching times as a function of collector current**  
 ( $T_j=150^{\circ}\text{C}$ ,  $V_{\text{CE}}=400\text{V}$ ,  $R_{\text{G(on)}}=R_{\text{G(off)}}=10\Omega$ )



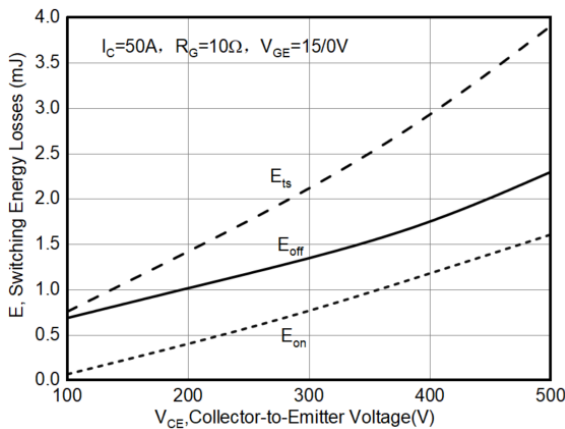
**Figure 14. Typical switching times as a function of gate resistance**  
 ( $T_j=150^{\circ}\text{C}$ ,  $V_{\text{CE}}=400\text{V}$ ,  $I_{\text{C}}=50\text{A}$ )



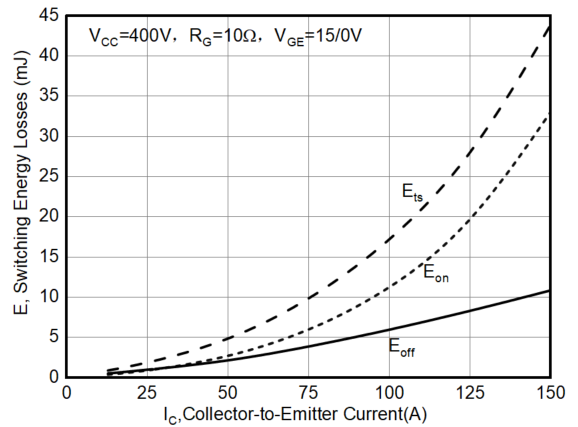
**Figure 15. Typical switching times as a function of junction temperature**  
 ( $V_{\text{CE}}=400\text{V}$ ,  $I_{\text{C}}=50\text{A}$ ,  $R_{\text{G(on)}}=R_{\text{G(off)}}=10\Omega$ )



**Figure 16.  $E_{\text{on}}$ ,  $E_{\text{off}}$  as a function of  $I_{\text{C}}$**   
 ( $T_j=25^{\circ}\text{C}$ )



**Figure 17.  $E_{\text{on}}$ ,  $E_{\text{off}}$  as a function of  $V_{\text{CE}}$**   
 ( $T_j=25^{\circ}\text{C}$ )



**Figure 18.  $E_{\text{on}}$ ,  $E_{\text{off}}$  as a function of  $I_{\text{C}}$**   
 ( $T_j=150^{\circ}\text{C}$ )

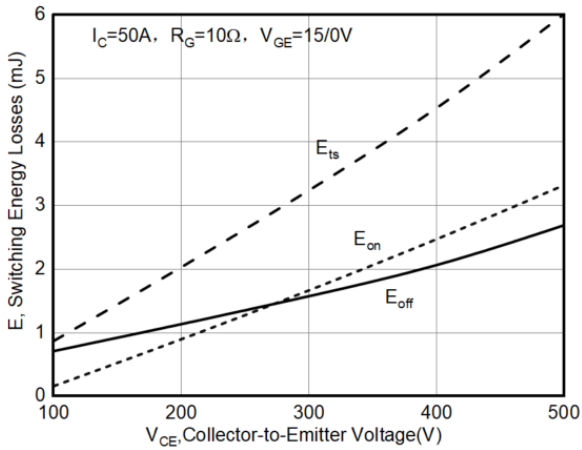


Figure 19.  $E_{on}$ ,  $E_{off}$  as a function of  $V_{CE}$  ( $T_j=150^\circ\text{C}$ )

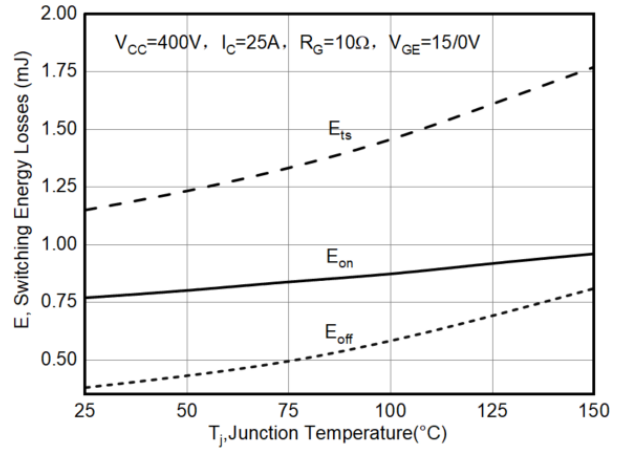


Figure 20.  $E_{on}$ ,  $E_{off}$  as a function of junction temperature

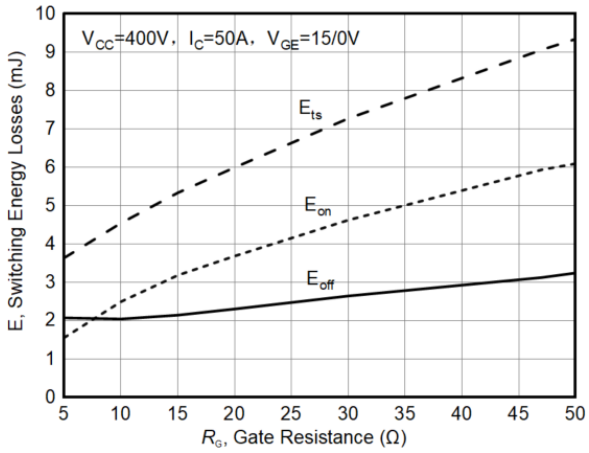


Figure 21.  $E_{on}$ ,  $E_{off}$  as a function of gate resistance ( $T_j=150^\circ\text{C}$ )

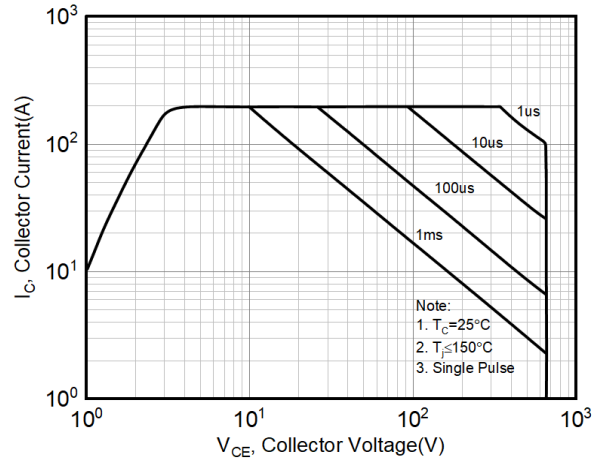
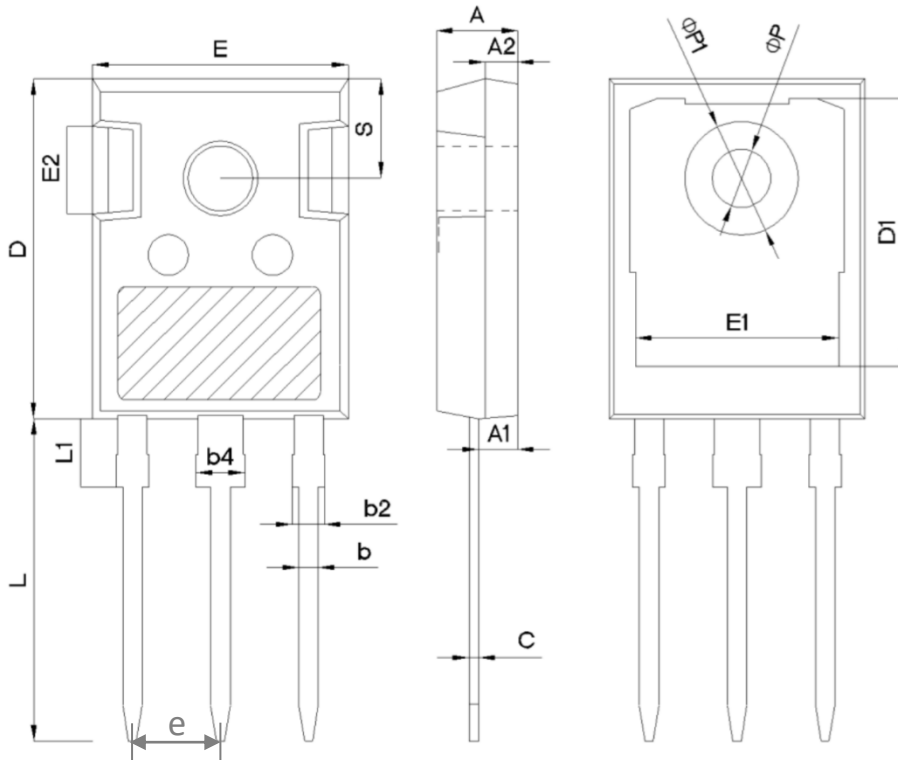


Figure 22. FBSOA

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SYMBOL	mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.61
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.70	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44BSC		
L	19.62	19.92	20.22
L1	-	-	4.30
ΦP	3.40	3.60	3.80
ΦP1	-	-	7.30
S	6.15BSC		





**Revision History:**

Revision	Date	Subjects (major changes since last revision)
1.0	2023-04-20	Initial Version
1.1	2023-05-09	Update the figure



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